## 16-Bit I/O Expander with Serial Interface

#### **Features**

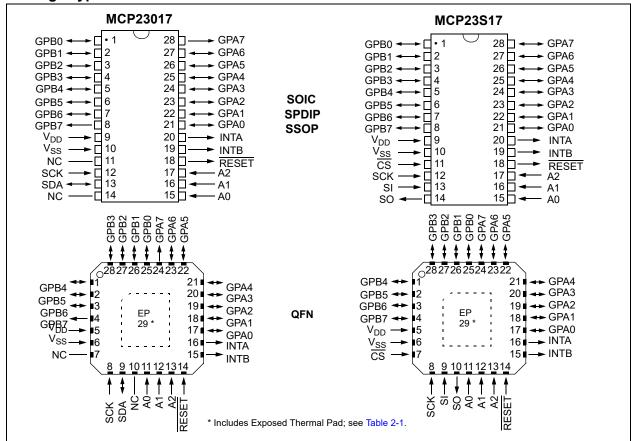
- AEC-Q100 Qualified
- 16-Bit Remote Bidirectional I/O Port (Pins GPA7, GPB7 are output only for **MCP23017**):
  - I/O pins default to input
- High-Speed I<sup>2</sup>C Interface (MCP23017):
  - 100 kHz
  - 400 kHz
  - 1.7 MHz
- High-Speed SPI Interface (MCP23S17):
  - 10 MHz (maximum)
- Three Hardware Address Pins to Allow Up to Eight Devices On the Bus
- Configurable Interrupt Output Pins:
  - Configurable as active-high, active-low or open-drain
- INTA and INTB Can Be Configured to Operate Independently or Together

- Configurable Interrupt Source:
  - Interrupt-on-change from configured register defaults or pin changes
- Polarity Inversion Register to Configure the Polarity of the Input Port Data
- · External Reset Input
- Low Standby Current: 1 μA (max.)
- · Operating Voltage:
  - 1.8V to 5.5V @ -40°C to +85°C
  - 2.7V to 5.5V @ -40°C to +85°C
  - 4.5V to 5.5V @ -40°C to +125°C

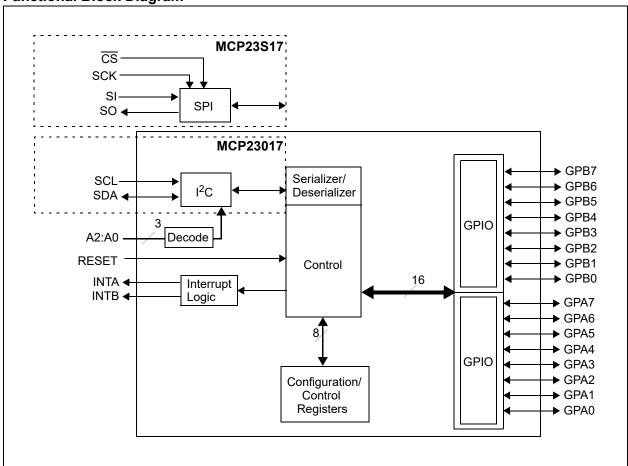
### **Packages**

- 28-pin QFN, 6 x 6 mm Body
- · 28-pin SOIC, Wide, 7.50 mm Body
- 28-pin SPDIP, 300 mil Body
- 28-pin SSOP, 5.30 mm Body

### **Package Types**



## **Functional Block Diagram**



## 1.0 ELECTRICAL CHARACTERISTICS

## **Absolute Maximum Ratings †**

Ambient temperature under bias	40°C to +125°C
Storage temperature	65°C to +150°C
Voltage on V <sub>DD</sub> with respect to V <sub>SS</sub>	0.3V to +5.5V
Voltage on all other pins with respect to V <sub>SS</sub> (except V <sub>DD</sub> )	–0.6V to (V <sub>DD</sub> + 0.6V)
Total power dissipation	700 mW
Maximum current out of V <sub>SS</sub> pin	150 mA
Maximum current into V <sub>DD</sub> pin	125 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{DD}$ )	±20 mA
Output clamp current, lok ( $V_O < 0$ or $V_O > V_{DD}$ )	±20 mA
Maximum output current sunk by any output pin	25 mA
Maximum output current sourced by any output pin	25 mA
ESD protection on all pins (HBM:MM)	4 kV:400V

<sup>†</sup> Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

### 1.1 DC Characteristics

TABLE 1-1: DC CHARACTERISTICS

			1				
Param. No.	Characteristic	Sym.	Min.	Typ. <sup>(1)</sup>	Max.	Units	Conditions
D001	Supply Voltage	V <sub>DD</sub>	1.8		5.5	<b>V</b>	
D002	V <sub>DD</sub> Start Voltage to ensure Power-on Reset	$V_{POR}$	_	$V_{SS}$		٧	
D003	V <sub>DD</sub> Rise Rate to ensure Power-on Reset	SV <sub>DD</sub>	0.05	_	_	V/ms	Design guidance only. Not tested.
D004	Supply Current	I <sub>DD</sub>	_	_	1	mA	SCL/SCK = 1 MHz
D005	Standby current	I <sub>DDS8</sub>	_	_	1	μΑ	$-40$ °C $\leq$ T <sub>A</sub> $\leq$ +85°C
			_	_	3	μA	$4.5V \le V_{DD} \le 5.5V + 85^{\circ}C \le T_{A} \le +125^{\circ}C$ (Note 1)
Input Lo	w Voltage						
D030	A0, A1, A2 (TTL buffer)	$V_{IL}$	V <sub>SS</sub>		0.15 V <sub>DD</sub>	V	
D031	CS, GPIO, SCL/SCK, SDA, RESET (Schmitt Trigger)	V <sub>IL</sub>	V <sub>SS</sub>	_	0.2 V <sub>DD</sub>	٧	
Input Hi	gh Voltage						
D040	A0, A1, A2 (TTL buffer)	V <sub>IH</sub>	0.25 VDD + 0.8	_	V <sub>DD</sub>	V	
D041	CS, GPIO, SCL/SCK, SDA, RESET (Schmitt Trigger)	V <sub>IH</sub>	0.8 VDD	_	V <sub>DD</sub>	V	For entire V <sub>DD</sub> range
Input Le	akage Current						
D060	I/O port pins	I <sub>IL</sub>	_	_	±1	μΑ	$V_{SS} \le V_{PIN} \le V_{DD}$
Output l	Leakage Current						
D065	I/O port pins	I <sub>LO</sub>	_	_	±1	μΑ	$V_{SS} \le V_{PIN} \le V_{DD}$
D070	GPIO weak pull-up current	I <sub>PU</sub>	40	75	115	μΑ	V <sub>DD</sub> = 5V GP pins = V <sub>SS</sub>
Output l	Low-Voltage						
D080	GPIO	V <sub>OL</sub>	_	_	0.6	V	I <sub>OL</sub> = 8.0 mA V <sub>DD</sub> = 4.5V
	INT	V <sub>OL</sub>	_	_	0.6	V	I <sub>OL</sub> = 1.6 mA V <sub>DD</sub> = 4.5V
	SO, SDA	V <sub>OL</sub>	_	_	0.6	V	I <sub>OL</sub> = 3.0 mA V <sub>DD</sub> = 1.8V
	SDA	V <sub>OL</sub>	_	_	0.8	V	I <sub>OL</sub> = 3.0 mA V <sub>DD</sub> = 4.5V
Output l	High-Voltage						
D090	GPIO, INT, SO	V <sub>OH</sub>	V <sub>DD</sub> – 0.7	_	_	V	$I_{OH} = -3.0 \text{ mA}$ $V_{DD} = 4.5 \text{V}$
			V <sub>DD</sub> – 0.7	_	_		I <sub>OH</sub> = -400 μA V <sub>DD</sub> = 1.8V
Capacit	ve Loading Specs on Out	put Pins					
D101	GPIO, SO, INT	C <sub>IO</sub>	_		50	pF	
D102	SDA	C <sub>B</sub>			400	pF	

Note 1: This parameter is characterized, not 100% tested.

### 1.2 AC Characteristics

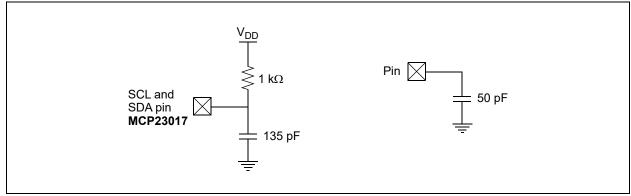


FIGURE 1-1: Load Conditions for device Timing Specifications.

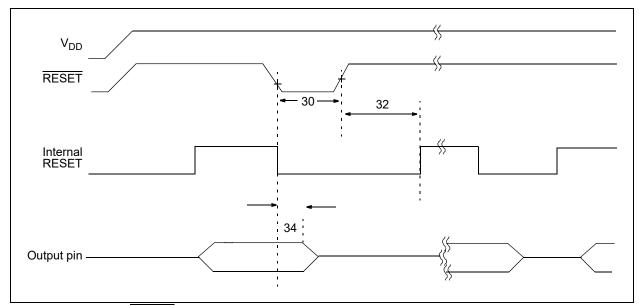


FIGURE 1-2: RESET and Device Reset Timer Timing.

TABLE 1-2: DEVICE RESET SPECIFICATIONS

AC Cha	<b>AC Characteristics:</b> Unless otherwise noted, $1.8V \le V_{DD} \le 5.5V$ at $-40^{\circ}C \le T_{A} \le +125^{\circ}C$										
Param. No.	Characteristic	Sym.	Min.	Typ. <sup>(1)</sup>	Max.	Units	Conditions				
30	RESET Pulse Width (Low)	T <sub>RSTL</sub>	1	_	_	μs					
32	Device Active After Reset high	T <sub>HLD</sub>	_	0	_	ns	V <sub>DD</sub> = 5.0V				
34	Output High-Impedance From RESET Low	T <sub>IOZ</sub>	_	_	1	μs					

Note 1: This parameter is characterized, not 100% tested.

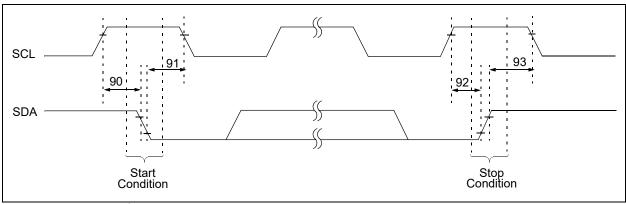


FIGURE 1-3: I<sup>2</sup>C Bus Start/Stop Bits Timing.

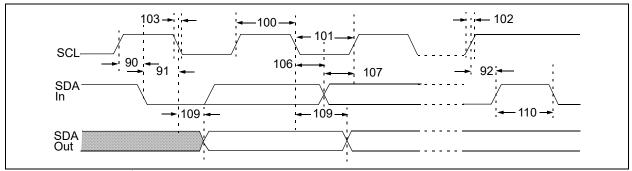


FIGURE 1-4: I<sup>2</sup>C Bus Data Timing.

TABLE 1-3: I<sup>2</sup>C BUS DATA REQUIREMENTS

**I**<sup>2</sup>C Interface AC Characteristics: Unless otherwise noted, 1.8V  $\leq$  V<sub>DD</sub>  $\leq$  5.5V at  $-40^{\circ}$ C  $\leq$  T<sub>A</sub>  $\leq$  +125°C, R<sub>PU</sub> (SCL, SDA) = 1 kΩ, C<sub>L</sub> (SCL, SDA) = 135 pF

Param.	Characteristic	Sym.	Min.	Тур.	Max.	Units	Conditions
No.							
100	Clock High Time:	T <sub>HIGH</sub>					
	100 kHz mode		4.0	_	_	μs	1.8V – 5.5V
	400 kHz mode		0.6	_	_	μs	2.7V - 5.5V
	1.7 MHz mode		0.12	_	_	μs	4.5V – 5.5V
101	Clock Low Time:	$T_{LOW}$					
	100 kHz mode		4.7	_	_	μs	1.8V – 5.5V
	400 kHz mode		1.3	_	_	μs	2.7V - 5.5V
	1.7 MHz mode		0.32	_	_	μs	4.5V – 5.5V
102	SDA and SCL Rise Time:	T <sub>R</sub> <sup>(1)</sup>					
	100 kHz mode		_	_	1000	ns	1.8V – 5.5V
	400 kHz mode		20 + 0.1 C <sub>B</sub> <sup>(2)</sup>	_	300	ns	2.7V - 5.5V
	1.7 MHz mode		20	_	160	ns	4.5V – 5.5V
103	SDA and SCL Fall Time:	T <sub>F</sub> (1)					
	100 kHz mode		_	_	300	ns	1.8V – 5.5V
	400 kHz mode		20 + 0.1 C <sub>B</sub> <sup>(2)</sup>	_	300	ns	2.7V - 5.5V
	1.7 MHz mode		20	_	80	ns	4.5V – 5.5V

**Note 1:** This parameter is characterized, not 100% tested.

2:  $C_B$  is specified to be from 10 to 400 pF.

## TABLE 1-3: I<sup>2</sup>C BUS DATA REQUIREMENTS (CONTINUED)

**I**<sup>2</sup>C Interface AC Characteristics: Unless otherwise noted, 1.8V  $\leq$  V<sub>DD</sub>  $\leq$  5.5V at  $-40^{\circ}$ C  $\leq$  T<sub>A</sub>  $\leq$  +125°C, R<sub>PU</sub> (SCL, SDA) = 1 kΩ, C<sub>L</sub> (SCL, SDA) = 135 pF

Param. No.	Characteristic	Sym.	Min.	Тур.	Max.	Units	Conditions
90	START Condition Setup Time:	T <sub>SU:STA</sub>					
	100 kHz mode		4.7	_	_	μs	1.8V – 5.5V
	400 kHz mode		0.6	_	_	μs	2.7V – 5.5V
	1.7 MHz mode		0.16	_	_	μs	4.5V – 5.5V
91	START Condition Hold Time:	T <sub>HD:STA</sub>					
	100 kHz mode		4.0	_		μs	1.8V – 5.5V
	400 kHz mode		0.6	_		μs	2.7V – 5.5V
	1.7 MHz mode		0.16	_	_	μs	4.5V – 5.5V
106	Data Input Hold Time:	T <sub>HD:DAT</sub>					
	100 kHz mode		0	_	3.45	μs	1.8V – 5.5V
	400 kHz mode		0	_	0.9	μs	2.7V - 5.5V
	1.7 MHz mode		0	_	0.15	μs	4.5V – 5.5V
107	Data Input Setup Time:	T <sub>SU:DAT</sub>					
	100 kHz mode		250	_	_	ns	1.8V – 5.5V
	400 kHz mode		100	_	_	ns	2.7V - 5.5V
	1.7 MHz mode		0.01	_	_	μs	4.5V – 5.5V
92	Stop Condition Setup Time:	T <sub>SU:STO</sub>					
	100 kHz mode		4.0	_	_	μs	1.8V – 5.5V
	400 kHz mode		0.6	_	_	μs	2.7V - 5.5V
	1.7 MHz mode		0.16	_		μs	4.5V-5.5V
109	Output Valid From Clock:	T <sub>AA</sub>					
	100 kHz mode		_	_	3.45	μs	1.8V – 5.5V
	400 kHz mode		_	_	0.9	μs	2.7V – 5.5V
	1.7 MHz mode		_	_	0.18	μs	4.5V – 5.5V
110	Bus Free Time:	T <sub>BUF</sub>					
	100 kHz mode		4.7	_	_	μs	1.8V – 5.5V
	400 kHz mode		1.3	_	_	μs	2.7V - 5.5V
	1.7 MHz mode		N/A	_	N/A	μs	4.5V – 5.5V
111	Bus Capacitive Loading:	C <sub>B</sub>					
	100 kHz and 400 kHz		_	_	400	pF	Note 1
	1.7 MHz		_	_	100	pF	Note 1
112	Input Filter Spike Suppression (SDA and SCL):	T <sub>SP</sub>					
	100 kHz and 400 kHz		_	_	50	ns	
	1.7 MHz		_	_	10	ns	Spike suppression off

**Note 1:** This parameter is characterized, not 100% tested.

<sup>2:</sup>  $C_B$  is specified to be from 10 to 400 pF.

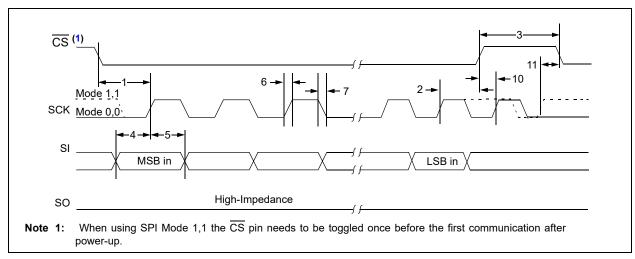


FIGURE 1-5: SPI Input Timing.

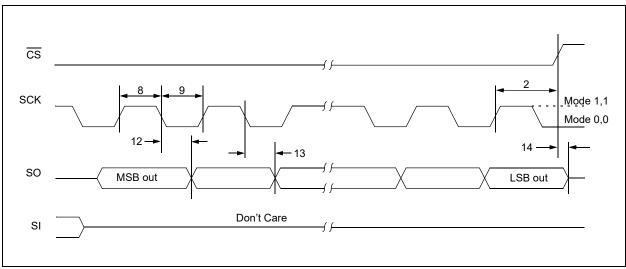


FIGURE 1-6: SPI Output Timing.

TABLE 1-4: SPI INTERFACE REQUIREMENTS

SPI Inter	<b>SPI Interface AC Characteristics:</b> Unless otherwise noted, $1.8V \le V_{DD} \le 5.5V$ at $-40^{\circ}C \le T_{A} \le +125^{\circ}C$									
Param. No.	Characteristic	Sym.	Min.	Тур.	Max.	Units	Conditions			
_	Clock Frequency	F <sub>CLK</sub>	_	_	5	MHz	1.8V – 5.5V			
				_	10	MHz	2.7V – 5.5V			
			_	1	10	MHz	4.5V – 5.5V			
1	CS Setup Time	T <sub>CSS</sub>	50			ns				
2	CS Hold Time	$T_{CSH}$	100	_		ns	1.8V – 5.5V			
			50			ns	2.7V – 5.5V			
3	CS Disable Time	$T_{CSD}$	100			ns	1.8V – 5.5V			
			50	_		ns	2.7V – 5.5V			
4	Data Setup Time	T <sub>SU</sub>	20			ns	1.8V – 5.5V			
			10		_	ns	2.7V – 5.5V			

Note 1: This parameter is characterized, not 100% tested.

TABLE 1-4: SPI INTERFACE REQUIREMENTS (CONTINUED)

SPI Inter	<b>SPI Interface AC Characteristics:</b> Unless otherwise noted, $1.8V \le V_{DD} \le 5.5V$ at $-40^{\circ}C \le T_{A} \le +125^{\circ}C$									
Param. No.	Characteristic	Sym.	Min.	Тур.	Max.	Units	Conditions			
5	Data Hold Time	T <sub>HD</sub>	20		_	ns	1.8V – 5.5V			
			10	_	_	ns	2.7V - 5.5V			
6	CLK Rise Time	$T_{R}$		_	2	μs	Note 1			
7	CLK Fall Time	T <sub>F</sub>		_	2	μs	Note 1			
8	Clock High Time	T <sub>HI</sub>	90	_	_	ns	1.8V – 5.5V			
			45			ns	2.7V - 5.5V			
9	Clock Low Time	$T_LO$	90	_		ns	1.8V – 5.5V			
			45			ns	2.7V – 5.5V			
10	Clock Delay Time	$T_{CLD}$	50		_	ns				
11	Clock Enable Time	$T_CLE$	50	_	_	ns				
12	Output Valid from Clock Low	T <sub>V</sub>		_	90	ns	1.8V – 5.5V			
				_	45	ns	2.7V - 5.5V			
13	Output Hold Time	T <sub>HO</sub>	0		_	ns				
14	Output Disable Time	$T_{DIS}$			100	ns				

Note 1: This parameter is characterized, not 100% tested.

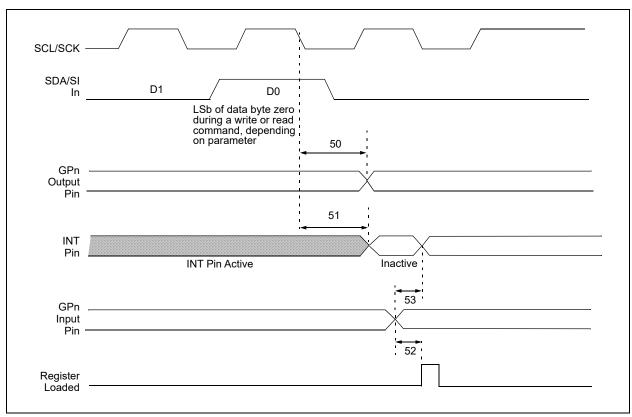


FIGURE 1-7: GPIO and INT Timing.

TABLE 1-5: GP AND INT PINS REQUIREMENTS

GP and IN	GP and INT Pins AC Characteristics: Unless otherwise noted, $1.8V \le V_{DD} \le 5.5V$ at $-40^{\circ}C \le T_{A} \le +125^{\circ}C$										
Param. No.	Characteristic	Sym.	Min.	Тур.	Max.	Units	Conditions				
50	Serial Data to Output Valid	T <sub>GPOV</sub>	_		500	ns					
51	Interrupt Pin Disable Time	T <sub>INTD</sub>	_	_	600	ns					
52	GP Input Change to Register Valid	T <sub>GPIV</sub>	_	_	450	ns					
53	IOC Event to INT Active	T <sub>GPINT</sub>	_	_	600	ns					
	Glitch Filter on GP Pins	T <sub>GLITCH</sub>	_	_	150	ns	Note 1				

**Note 1:** This parameter is characterized, not 100% tested.

## 2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PINOUT DESCRIPTION

Pin Name	QFN	SOIC SPDIP SSOP	Pin Type	Function
GPB0	25	1	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPB1	26	2	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPB2	27	3	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPB3	28	4	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPB4	1	5	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPB5	2	6	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPB6	3	7	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPB7	4	8	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor./ Output only (MCP23017).
$V_{DD}$	5	9	Р	Power
V <sub>SS</sub>	6	10	Р	Ground
NC/CS	7	11	I	NC (MCP23017)/Chip Select (MCP23S17)
SCK	8	12	I	Serial clock input
SDA/SI	9	13	I/O	Serial data I/O (MCP23017)/Serial data input (MCP23S17)
NC/SO	10	14	0	NC (MCP23017)/Serial data out (MCP23S17)
A0	11	15	I	Hardware address pin. Must be externally biased.
A1	12	16	I	Hardware address pin. Must be externally biased.
A2	13	17	I	Hardware address pin. Must be externally biased.
RESET	14	18	I	Hardware reset. Must be externally biased.
INTB	15	19	0	Interrupt output for PORTB. Can be configured as active-high, active-low or open-drain.
INTA	16	20	0	Interrupt output for PORTA. Can be configured as active-high, active-low or open-drain.
GPA0	17	21	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPA1	18	22	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPA2	19	23	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPA3	20	24	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPA4	21	25	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPA5	22	26	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPA6	23	27	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor.
GPA7	24	28	I/O	Bidirectional I/O pin. Can be enabled for interrupt-on-change and/or internal weak pull-up resistor./ Output only (MCP23017).
EP	29	_	_	Exposed Thermal Pad. Either connect to V <sub>SS</sub> , or leave unconnected.

#### 3.0 DEVICE OVERVIEW

MCP23017/MCP23S17 (MCP23X17) device family provides 16-bit, general purpose parallel I/O expansion for I<sup>2</sup>C bus or SPI applications. The two devices differ only in the serial interface:

- MCP23017 I<sup>2</sup>C interface
- MCP23S17 SPI interface

MCP23X17 consists of multiple 8-bit configuration registers for input, output and polarity selection. The system host can enable the I/Os as either inputs or outputs by writing the I/O configuration bits (IODIRA/B). The data for each input or output is kept in the corresponding input or output register. The polarity of the Input Port register can be inverted with the Polarity Inversion register. All registers can be read by the system host.

The 16-bit I/O port functionally consists of two 8-bit ports (PORTA and PORTB). MCP23X17 can be configured to operate in the 8-bit or 16-bit modes via IOCON.BANK.

There are two interrupt pins, INTA and INTB, that can be associated with their respective ports, or can be logically OR'ed together so that both pins will activate if either port causes an interrupt.

The interrupt output can be configured to activate under two conditions (mutually exclusive):

- When any input state differs from its corresponding Input Port register state. This is used to indicate to the system host that an input state has changed.
- When an input state differs from a preconfigured register value (DEFVAL register).

The Interrupt Capture register captures port values at the time of the interrupt, thereby saving the condition that caused the interrupt.

The Power-on Reset (POR) sets the registers to their default values and initializes the device state machine.

The hardware address pins are used to determine the device address.

#### 3.1 Power-on Reset (POR)

The on-chip POR circuit holds the device in reset until  $V_{DD}$  has reached a high enough voltage to deactivate the POR circuit (i.e., release the device from reset). The maximum  $V_{DD}$  rise time is specified in **Section 1.0** "Electrical Characteristics".

When the device exits the POR condition (releases reset), device operating parameters (i.e., voltage, temperature, serial bus frequency, etc.) must be met to ensure proper operation.

#### 3.2 Serial Interface

This block handles the functionality of the  $I^2C$  (MCP23017) or SPI (MCP23S17) interface protocol. MCP23X17 contains 22 individual registers (11 register pairs) that can be addressed through the Serial Interface block, as shown in Table 3-1.

TABLE 3-1: REGISTER ADDRESSES

IABLE 3-1. I	COOTEN ADDICE	.0020
Address IOCON.BANK = 1	Address IOCON.BANK = 0	Access to:
00h	00h	IODIRA
10h	01h	IODIRB
01h	02h	IPOLA
11h	03h	IPOLB
02h	04h	GPINTENA
12h	05h	GPINTENB
03h	06h	DEFVALA
13h	07h	DEFVALB
04h	08h	INTCONA
14h	09h	INTCONB
05h	0Ah	IOCON
15h	0Bh	IOCON
06h	0Ch	GPPUA
16h	0Dh	GPPUB
07h	0Eh	INTFA
17h	0Fh	INTFB
08h	10h	INTCAPA
18h	11h	INTCAPB
09h	12h	GPIOA
19h	13h	GPIOB
0Ah	14h	OLATA
1Ah	15h	OLATB

## 3.2.1 BYTE MODE AND SEQUENTIAL MODE

MCP23X17 family has the ability to operate in Byte mode or Sequential mode (IOCON.SEQOP).

Byte mode disables automatic Address Pointer incrementing. When operating in Byte mode, MCP23X17 family does not increment its internal address counter after each byte during the data transfer. This gives the ability to continually access the same address by providing extra clocks (without additional control bytes). This is useful for polling the GPIO register for data changes or for continually writing to the output latches.

A special mode (Byte mode with IOCON.BANK = 0) causes the address pointer to toggle between associated A/B register pairs. For example, if the BANK bit is cleared and the Address Pointer is initially set to address 12h (GPIOA) or 13h (GPIOB), the pointer will toggle between GPIOA and GPIOB. Note that the Address Pointer can initially point to either address in the register pair.

**Sequential mode** enables automatic address pointer incrementing. When operating in Sequential mode, MCP23X17 family increments its address counter after each byte during the data transfer. The Address Pointer automatically rolls over to address 00h after accessing the last register.

These two modes are not to be confused with single writes/reads and continuous writes/reads that are serial protocol sequences. For example, the device may be configured for Byte mode and the host may perform a continuous read. In this case, MCP23X17 would not increment the Address Pointer and would repeatedly drive data from the same location.

### 3.2.2 I<sup>2</sup>C INTERFACE

## 3.2.2.1 I<sup>2</sup>C Write Operation

The I<sup>2</sup>C write operation includes the control byte and register address sequence, as shown in Figure 3-1. This sequence is followed by eight bits of data from the host and an Acknowledge (ACK) from the MCP23017. The operation is ended with a Stop (P) or Restart (SR) condition being generated by the host.

Data is written to MCP23017 after every byte transfer. If a Stop or Restart condition is generated during a data transfer, the data will not be written to MCP23017.

Both "byte writes" and "sequential writes" are supported by MCP23017. If Sequential mode is enabled (IOCON, SEQOP = 0) (default), MCP23017 increments its address counter after each ACK during the data transfer.

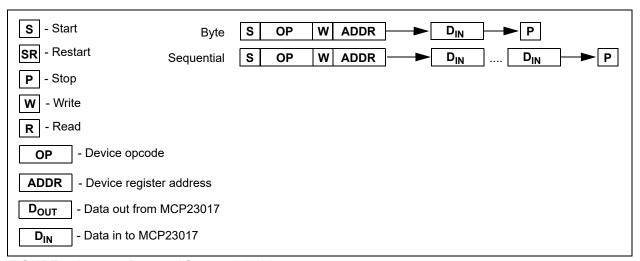


FIGURE 3-1: Byte and Sequential Write.

### 3.2.2.2 I<sup>2</sup>C Read Operation

 $I^2C$  Read operations include the control byte sequence, as shown in Figure 3-2. This sequence is followed by another control byte (including the Start condition and ACK) with the R/W bit set (R/W = 1). The MCP23017 then transmits the data contained in the addressed register. The sequence is ended with the host generating a Stop or Restart condition.

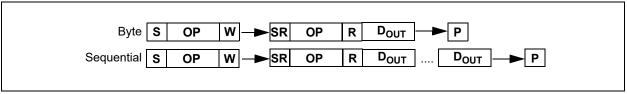


FIGURE 3-2: Byte and Sequential Read.

## 3.2.2.3 I<sup>2</sup>C Sequential Write/Read

For sequential operations (Write or Read), instead of transmitting a Stop or Restart condition after the data transfer, the host clocks the next byte pointed to by the address pointer (see Section 3.2.1 "Byte Mode and Sequential Mode" for details regarding sequential operation control).

The sequence ends with the host sending a Stop or Restart condition.

MCP23017 Address Pointer will roll over to address zero after reaching the last register address. Refer to Figure 3-3.

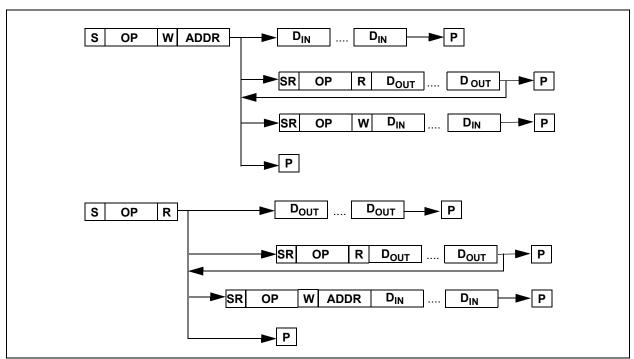


FIGURE 3-3: MCP23017 I<sup>2</sup>C Device Protocol.

#### 3.2.3 SPI INTERFACE

#### 3.2.3.1 SPI Write Operation

The SPI write operation is started by lowering  $\overline{CS}$ . The Write command (client address with R/W bit cleared) is then clocked into the device. The opcode is followed by an address and at least one data byte.

#### 3.2.3.2 SPI Read Operation

The SPI read operation is started by lowering  $\overline{CS}$ . The SPI read command (client address with R/W bit set) is then clocked into the device. The opcode is followed by an address, with at least one data byte being clocked out of the device.

#### 3.2.3.3 SPI Seguential Write/Read

For sequential operations, instead of deselecting the device by raising  $\overline{CS}$ , the host clocks the next byte pointed to by the Address Pointer. (see Section 3.2.1 "Byte Mode and Sequential Mode" for details regarding sequential operation control).

The sequence ends by the raising of  $\overline{CS}$ .

MCP23S17 Address Pointer will roll over to address zero after reaching the last register address.

#### 3.3 Hardware Address Decoder

The hardware address pins are used to determine the device address. To address a device, the corresponding address bits in the control byte must match the pin state. The pins must be biased externally.

# 3.3.1 ADDRESSING I<sup>2</sup>C DEVICES (MCP23017)

MCP23017 is a client I<sup>2</sup>C interface device that supports 7-bit client addressing, with the read/write bit filling out the control byte. The client address contains four fixed

bits and three user-defined hardware address bits (pins A2, A1 and A0). Figure 3-4 shows the control byte format

## 3.3.2 ADDRESSING SPI DEVICES (MCP23S17)

MCP23S17 is a client SPI device. The client address contains four fixed bits and three user-defined hardware address bits (if enabled via IOCON.HAEN) (pins A2, A1 and A0) with the read/write bit filling out the control byte. Figure 3-5 shows the control byte format. The address pins should be externally biased even if disabled (IOCON.HAEN = 0).

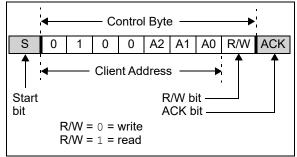


FIGURE 3-4: I<sup>2</sup>C Control Byte Format.

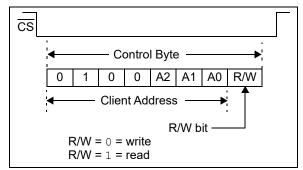


FIGURE 3-5: SPI Control Byte Format.

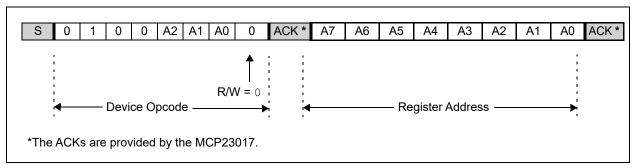


FIGURE 3-6: I<sup>2</sup>C Addressing Registers.

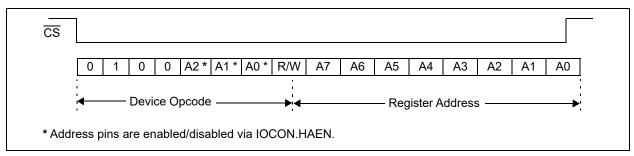


FIGURE 3-7: SPI Addressing Registers.

#### 3.4 GPIO Port

The GPIO module is a general purpose, 16-bit wide, bidirectional port that is functionally split into two 8-bit wide ports.

The GPIO module contains the data ports (GPIOn), internal pull-up resistors and the output latches (OLATn).

Reading the GPIOn register reads the value on the port. Reading the OLATn register only reads the latches, not the actual value on the port.

Writing to the GPIOn register actually causes a write to the latches (OLATn). Writing to the OLATn register forces the associated output drivers to drive to the level in OLATn. Pins configured as inputs turn off the associated output driver and put it in high-impedance.

TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH THE GPIO PORTS (BANK = 1)

Register Name	Address (hex)	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	POR/RST value
IODIRA	00	107	106	IO5	IO4	IO3	102	IO1	IO0	1111 1111
IPOLA	01	IP7	IP6	IP5	IP4	IP3	IP2	IP1	IP0	0000 0000
GPINTENA	02	GPINT7	GPINT6	GPINT5	GPINT4	GPINT3	GPINT2	GPINT1	GPINT0	0000 0000
GPPUA	06	PU7	PU6	PU5	PU4	PU3	PU2	PU1	PU0	0000 0000
GPIOA	09	GP7	GP6	GP5	GP4	GP3	GP2	GP1	GP0	0000 0000
OLATA	0A	OL7	OL6	OL5	OL4	OL3	OL2	OL1	OL0	0000 0000
IODIRB	10	107	106	IO5	IO4	IO3	102	IO1	IO0	1111 1111
IPOLB	11	IP7	IP6	IP5	IP4	IP3	IP2	IP1	IP0	0000 0000
GPINTENB	12	GPINT7	GPINT6	GPINT5	GPINT4	GPINT3	GPINT2	GPINT1	GPINT0	0000 0000
GPPUB	16	PU7	PU6	PU5	PU4	PU3	PU2	PU1	PU0	0000 0000
GPIOB	19	GP7	GP6	GP5	GP4	GP3	GP2	GP1	GP0	0000 0000
OLATB	1A	OL7	OL6	OL5	OL4	OL3	OL2	OL1	OL0	0000 0000

TABLE 3-3: SUMMARY OF REGISTERS ASSOCIATED WITH THE GPIO PORTS (BANK = 0)

Register Name	Address (hex)	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	POR/RST value
IODIRA	00	107	106	IO5	IO4	IO3	IO2	IO1	IO0	1111 1111
IODIRB	01	107	106	105	104	IO3	102	IO1	100	1111 1111
IPOLA	02	IP7	IP6	IP5	IP4	IP3	IP2	IP1	IP0	0000 0000
IPOLB	03	IP7	IP6	IP5	IP4	IP3	IP2	IP1	IP0	0000 0000
GPINTENA	04	GPINT7	GPINT6	GPINT5	GPINT4	GPINT3	GPINT2	GPINT1	GPINT0	0000 0000
GPINTENB	05	GPINT7	GPINT6	GPINT5	GPINT4	GPINT3	GPINT2	GPINT1	GPINT0	0000 0000
GPPUA	0C	PU7	PU6	PU5	PU4	PU3	PU2	PU1	PU0	0000 0000
GPPUB	0D	PU7	PU6	PU5	PU4	PU3	PU2	PU1	PU0	0000 0000
GPIOA	12	GP7	GP6	GP5	GP4	GP3	GP2	GP1	GP0	0000 0000
GPIOB	13	GP7	GP6	GP5	GP4	GP3	GP2	GP1	GP0	0000 0000
OLATA	14	OL7	OL6	OL5	OL4	OL3	OL2	OL1	OL0	0000 0000
OLATB	15	OL7	OL6	OL5	OL4	OL3	OL2	OL1	OL0	0000 0000

# 3.5 Configuration and Control Registers

There are 21 registers associated with the MCP23X17, as shown in Tables 3-4 and 3-5. The two tables show the register mapping with the two BANK bit values. Ten registers are associated with PORTA and ten are

associated with PORTB. One register (IOCON) is shared between the two ports. The PORTA registers are identical to the PORTB registers, therefore, they will be referred to without differentiating between the port designation (i.e., they will not have the "A" or "B" designator assigned) in the register tables.

TABLE 3-4: CONTROL REGISTER SUMMARY (IOCON.BANK = 1)

Register Name	Address (hex)	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	POR/RST value
IODIRA	00	107	106	IO5	IO4	IO3	IO2	IO1	100	1111 1111
IPOLA	01	IP7	IP6	IP5	IP4	IP3	IP2	IP1	IP0	0000 0000
GPINTENA	02	GPINT7	GPINT6	GPINT5	GPINT4	GPINT3	GPINT2	GPINT1	GPINT0	0000 0000
DEFVALA	03	DEF7	DEF6	DEF5	DEF4	DEF3	DEF2	DEF1	DEF0	0000 0000
INTCONA	04	IOC7	IOC6	IOC5	IOC4	IOC3	IOC2	IOC1	IOC0	0000 0000
IOCON	05	BANK	MIRROR	SEQOP	DISSLW	HAEN	ODR	INTPOL	_	0000 0000
GPPUA	06	PU7	PU6	PU5	PU4	PU3	PU2	PU1	PU0	0000 0000
INTFA	07	INT7	INT6	INT5	INT4	INT3	INT2	INT1	INTO	0000 0000
INTCAPA	08	ICP7	ICP6	ICP5	ICP4	ICP3	ICP2	ICP1	ICP0	0000 0000
GPIOA	09	GP7	GP6	GP5	GP4	GP3	GP2	GP1	GP0	0000 0000
OLATA	0A	OL7	OL6	OL5	OL4	OL3	OL2	OL1	OL0	0000 0000
IODIRB	10	107	106	105	104	IO3	102	IO1	100	1111 1111
IPOLB	11	IP7	IP6	IP5	IP4	IP3	IP2	IP1	IP0	0000 0000
GPINTENB	12	GPINT7	GPINT6	GPINT5	GPINT4	GPINT3	GPINT2	GPINT1	GPINT0	0000 0000
DEFVALB	13	DEF7	DEF6	DEF5	DEF4	DEF3	DEF2	DEF1	DEF0	0000 0000
INTCONB	14	IOC7	IOC6	IOC5	IOC4	IOC3	IOC2	IOC1	IOC0	0000 0000
IOCON	15	BANK	MIRROR	SEQOP	DISSLW	HAEN	ODR	INTPOL	_	0000 0000
GPPUB	16	PU7	PU6	PU5	PU4	PU3	PU2	PU1	PU0	0000 0000
INTFB	17	INT7	INT6	INT5	INT4	INT3	INT2	INT1	INTO	0000 0000
INTCAPB	18	ICP7	ICP6	ICP5	ICP4	ICP3	ICP2	ICP1	ICP0	0000 0000
GPIOB	19	GP7	GP6	GP5	GP4	GP3	GP2	GP1	GP0	0000 0000
OLATB	1A	OL7	OL6	OL5	OL4	OL3	OL2	OL1	OL0	0000 0000

TABLE 3-5: CONTROL REGISTER SUMMARY (IOCON.BANK = 0)

Register Name	Address (hex)	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	POR/RST value
IODIRA	00	107	106	IO5	IO4	IO3	IO2	IO1	100	1111 1111
IODIRB	01	107	106	IO5	104	IO3	102	IO1	100	1111 1111
IPOLA	02	IP7	IP6	IP5	IP4	IP3	IP2	IP1	IP0	0000 0000
IPOLB	03	IP7	IP6	IP5	IP4	IP3	IP2	IP1	IP0	0000 0000
GPINTENA	04	GPINT7	GPINT6	GPINT5	GPINT4	GPINT3	GPINT2	GPINT1	GPINT0	0000 0000
GPINTENB	05	GPINT7	GPINT6	GPINT5	GPINT4	GPINT3	GPINT2	GPINT1	GPINT0	0000 0000
DEFVALA	06	DEF7	DEF6	DEF5	DEF4	DEF3	DEF2	DEF1	DEF0	0000 0000
DEFVALB	07	DEF7	DEF6	DEF5	DEF4	DEF3	DEF2	DEF1	DEF0	0000 0000
INTCONA	08	IOC7	IOC6	IOC5	IOC4	IOC3	IOC2	IOC1	IOC0	0000 0000
INTCONB	09	IOC7	IOC6	IOC5	IOC4	IOC3	IOC2	IOC1	IOC0	0000 0000
IOCON	0A	BANK	MIRROR	SEQOP	DISSLW	HAEN	ODR	INTPOL	_	0000 0000
IOCON	0B	BANK	MIRROR	SEQOP	DISSLW	HAEN	ODR	INTPOL	_	0000 0000
GPPUA	0C	PU7	PU6	PU5	PU4	PU3	PU2	PU1	PU0	0000 0000
GPPUB	0D	PU7	PU6	PU5	PU4	PU3	PU2	PU1	PU0	0000 0000

TABLE 3-5: CONTROL REGISTER SUMMARY (IOCON.BANK = 0) (CONTINUED)

Register Name	Address (hex)	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	POR/RST value
INTFA	0E	INT7	INT6	INT5	INT4	INT3	INT2	INT1	INTO	0000 0000
INTFB	0F	INT7	INT6	INT5	INT4	INT3	INT2	INT1	INTO	0000 0000
INTCAPA	10	ICP7	ICP6	ICP5	ICP4	ICP3	ICP2	ICP1	ICP0	0000 0000
INTCAPB	11	ICP7	ICP6	ICP5	ICP4	ICP3	ICP2	ICP1	ICP0	0000 0000
GPIOA	12	GP7	GP6	GP5	GP4	GP3	GP2	GP1	GP0	0000 0000
GPIOB	13	GP7	GP6	GP5	GP4	GP3	GP2	GP1	GP0	0000 0000
OLATA	14	OL7	OL6	OL5	OL4	OL3	OL2	OL1	OL0	0000 0000
OLATB	15	OL7	OL6	OL5	OL4	OL3	OL2	OL1	OL0	0000 0000

#### 3.5.1 I/O DIRECTION REGISTER

Controls the direction of the data I/O.

When a bit is set, the corresponding pin becomes an input. When a bit is clear, the corresponding pin becomes an output.

#### **IODIR: I/O DIRECTION REGISTER (ADDR 0x00)**

| R/W-1 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| 107   | IO6   | IO5   | 104   | IO3   | IO2   | IO1   | IO0   |
| bit 7 |       |       |       |       |       |       | bit 0 |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 **IO<7:0>:** Controls the direction of data I/O <7:0>

1 = Pin is configured as an input.

0 = Pin is configured as an output.

**Note:** For **MCP23017**, IO7 must be set via I<sup>2</sup>C interface to "0" (output).

### 3.5.2 INPUT POLARITY REGISTER

This register allows the user to configure the polarity on the corresponding GPIO port bits.

If a bit is set, the corresponding GPIO register bit will reflect the inverted value on the pin.

#### REGISTER 3-1: IPOL: INPUT POLARITY PORT REGISTER (ADDR 0x01)

| R/W-0 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| IP7   | IP6   | IP5   | IP4   | IP3   | IP2   | IP1   | IP0   |
| bit 7 |       |       |       |       |       |       | bit 0 |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 **IP<7:0>:** Controls the polarity inversion of the input pins <7:0>

1 = GPIO register bit reflects the opposite logic state of the input pin.

0 = GPIO register bit reflects the same logic state of the input pin.

## 3.5.3 INTERRUPT-ON-CHANGE CONTROL REGISTER

The GPINTEN register controls the interrupt-on-change feature for each pin.

If a bit is set, the corresponding pin is enabled for interrupt-on-change. The DEFVAL and INTCON registers must also be configured if any pins are enabled for interrupt-on-change.

#### REGISTER 3-2: GPINTEN: INTERRUPT-ON-CHANGE PINS (ADDR 0x02) (Note 1)

| R/W-0  |
|--------|--------|--------|--------|--------|--------|--------|--------|
| GPINT7 | GPINT6 | GPINT5 | GPINT4 | GPINT3 | GPINT2 | GPINT1 | GPINT0 |
| bit 7  |        |        |        |        |        |        | bit 0  |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 **GPINT<7:0>:** General purpose I/O interrupt-on-change bits <7:0>

1 = Enables GPIO input pin for interrupt-on-change event.

0 = Disables GPIO input pin for interrupt-on-change event.

Note 1: Refer to INTCON.

## 3.5.4 DEFAULT COMPARE REGISTER FOR INTERRUPT-ON-CHANGE

The default comparison value is configured in the DEFVAL register. If enabled (via GPINTEN and INTCON) to compare against the DEFVAL register, an opposite value on the associated pin will cause an interrupt to occur.

#### REGISTER 3-3: DEFVAL: DEFAULT VALUE REGISTER (ADDR 0x03)

| R/W-0 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| DEF7  | DEF6  | DEF5  | DEF4  | DEF3  | DEF2  | DEF1  | DEF0  |
| bit 7 |       |       |       |       |       |       | bit 0 |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 **DEF<7:0>:** Sets the compare value for pins configured for interrupt-on-change from defaults <7:0>

If the associated pin level is the opposite from the register bit, an interrupt occurs. (Note 2)

Note 1: Refer to INTCON.

2: Refer to INTCON and GPINTEN.

#### 3.5.5 INTERRUPT CONTROL REGISTER

The INTCON register controls how the associated pin value is compared for the interrupt-on-change feature. If a bit is set, the corresponding I/O pin is compared against the associated bit in the DEFVAL register. If a bit value is clear, the corresponding I/O pin is compared against the previous value.

#### REGISTER 3-4: INTCON: INTERRUPT-ON-CHANGE CONTROL REGISTER (ADDR 0x04) (Note 1)

| R/W-0 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| IOC7  | IOC6  | IOC5  | IOC4  | IOC3  | IOC2  | IOC1  | IOC0  |
| bit 7 |       |       |       |       |       |       | bit 0 |

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **IOC<7:0>:** Controls how the associated pin value is compared for interrupt-on-change <7:0>

- 1 = Pin value is compared against the associated bit in the DEFVAL register.
- 0 = Pin value is compared against the previous pin value.

Note 1: Refer to INTCON and GPINTEN.

#### 3.5.6 CONFIGURATION REGISTER

The IOCON register contains several bits for configuring the device:

The BANK bit changes how the registers are mapped (see Tables 3-4 and 3-5 for more details).

- If BANK = 1, the registers associated with each port are segregated. Registers associated with PORTA are mapped from address 00h - 0Ah and registers associated with PORTB are mapped from 10h - 1Ah.
- If BANK = 0, the A/B registers are paired. For example, IODIRA is mapped to address 00h and IODIRB is mapped to the next address (address 01h). The mapping for all registers is from 00h -15h.

It is important to take care when changing the BANK bit as the address mapping changes after the byte is clocked into the device. The address pointer may point to an invalid location after the bit is modified.

For example, if the device is configured to automatically increment its internal Address Pointer, the following scenario would occur:

- BANK = 0
- Write 80h to address 0Ah (IOCON) to set the BANK bit
- Once the write completes, the internal address now points to 0Bh which is an invalid address when the BANK bit is set.

For this reason, when changing the BANK bit, it is advised to only perform byte writes to this register.

The **MIRROR** bit controls how the INTA and INTB pins function with respect to each other.

- When MIRROR = 1, the INTn pins are functionally OR'ed so that an interrupt on either port will cause both pins to activate.
- When MIRROR = 0, the INT pins are separated. Interrupt conditions on a port will cause its respective INT pin to activate.

The Sequential Operation (**SEQOP**) controls the incrementing function of the Address Pointer. If the address pointer is disabled, the Address Pointer does not automatically increment after each byte is clocked during a serial transfer. This feature is useful when it is desired to continuously poll (read) or modify (write) a register.

The Slew Rate (**DISSLW**) bit controls the slew rate function on the SDA pin. If enabled, the SDA slew rate will be controlled when driving from a high to low.

The Hardware Address Enable (HAEN) bit enables/disables hardware addressing on the MCP23S17 only. The address pins (A2, A1 and A0) must be externally biased, regardless of the HAEN bit value.

If enabled (HAEN = 1), the device's hardware address matches the address pins.

If disabled (HAEN = 0), the device's hardware address is A2 = A1 = A0 = 0.

The Open-Drain (**ODR**) control bit enables/disables the INT pin for open-drain configuration. Setting this bit overrides the INTPOL bit.

Legend:

R = Readable bit

The Interrupt Polarity (INTPOL) sets the polarity of the INT pin. This bit is functional only when the ODR bit is cleared, configuring the INT pin as active push-pull.

U = Unimplemented bit, read as '0'

### REGISTER 3-5: IOCON: I/O EXPANDER CONFIGURATION REGISTER (ADDR 0x05)

W = Writable bit

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
BANK	MIRROR	SEQOP	DISSLW	HAEN	ODR	INTPOL	_
bit 7							bit 0

IX - IXCAGADIC	W = Williable bit 0 = Offiniplemented bit, read as 0							
-n = Value at F	POR '1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown					
bit 7	<b>BANK:</b> Controls how the registers are a	ıddressed						
	<ul><li>1 = The registers associated with each</li><li>0 = The registers are in the same bank</li></ul>	•	ent banks.					
bit 6	MIRROR: INT Pins Mirror bit							
	1 = The INT pins are internally connected 0 = The INT pins are not connected. INT PORTB		and INTB is associated with					
bit 5	SEQOP: Sequential Operation mode bi	t						
	<ul><li>1 = Sequential operation disabled, add</li><li>0 = Sequential operation enabled, addr</li></ul>	•	ent.					
bit 4	DISSLW: Slew Rate control bit for SDA	output						
	<ul><li>1 = Slew rate disabled</li><li>0 = Slew rate enabled</li></ul>							
bit 3	HAEN: Hardware Address Enable bit (M	ICP23S17 only) (Note 1)						
	1 = Enables the MCP23S17 address pi	ns.						
	0 = Disables the MCP23S17 address p	ins.						
bit 2	ODR: Configures the INT pin as an ope	n-drain output						
	<ul><li>1 = Open-drain output (overrides the IN</li><li>0 = Active driver output (INTPOL bit set</li></ul>	,						
bit 1	INTPOL: This bit sets the polarity of the	INT output pin						
	<ul><li>1 = Active-high</li><li>0 = Active-low</li></ul>							
bit 0	Unimplemented: Read as '0'							

**Note 1:** Address pins are always enabled on the MCP23017.

## 3.5.7 PULL-UP RESISTOR CONFIGURATION REGISTER

The GPPU register controls the pull-up resistors for the port pins. If a bit is set and the corresponding pin is configured as an input, the corresponding port pin is internally pulled up with a 100 k $\Omega$  resistor.

#### REGISTER 3-6: GPPU: GPIO PULL-UP RESISTOR REGISTER (ADDR 0x06)

| R/W-0 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| PU7   | PU6   | PU5   | PU4   | PU3   | PU2   | PU1   | PU0   |
| bit 7 |       |       |       |       |       |       | bit 0 |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 PU<7:0> Controls the weak pull-up resistors on each pin (when configured as an input)

1 = Pull-up enabled

0 = Pull-up disabled

#### 3.5.8 INTERRUPT FLAG REGISTER

The INTF register reflects the interrupt condition on the port pins of any pin that is enabled for interrupts via the GPINTEN register. A set bit indicates that the associated pin caused the interrupt.

This register is read-only. Writes to this register will be ignored.

#### REGISTER 3-7: INTF: INTERRUPT FLAG REGISTER (ADDR 0x07)

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
INT7	INT6	INT5	INT4	INT3	INT2	INT1	INT0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 **INT<7:0>:** Reflects the interrupt condition on the port. It reflects the change only if interrupts are enabled per GPINTEN<7:0>.

1 = Pin caused interrupt.

0 = Interrupt not pending

#### 3.5.9 INTERRUPT CAPTURED REGISTER

The INTCAP register captures the GPIO port value at the time the interrupt occurred. The register is read-only and is updated only when an interrupt occurs. The register remains unchanged until the interrupt is cleared via a read of INTCAP or GPIO.

### REGISTER 3-8: INTCAP: INTERRUPT CAPTURED VALUE FOR PORT REGISTER (ADDR 0x08)

R-x	R-x	R-x	R-x	R-x	R-x	R-x	R-x
ICP7	ICP6	ICP5	ICP4	ICP3	ICP2	ICP1	ICP0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 ICP<7:0>: Reflects the logic level on the port pins at the time of interrupt due to pin change <7:0>

1 = Logic-high

0 = Logic-low

#### 3.5.10 PORT REGISTER

The GPIO register reflects the value on the port. Reading from this register reads the port. Writing to this register modifies the Output Latch (OLAT) register.

### REGISTER 3-9: GPIO: GENERAL PURPOSE I/O PORT REGISTER (ADDR 0x09)

| R/W-0 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| GP7   | GP6   | GP5   | GP4   | GP3   | GP2   | GP1   | GP0   |
| bit 7 |       |       |       |       |       |       | bit 0 |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 **GP<7:0>:** Reflects the logic level on the pins <7:0>

1 = Logic-high

0 = Logic-low

#### 3.5.11 OUTPUT LATCH REGISTER (OLAT)

The OLAT register provides access to the output latches. A read from this register results in a read of the OLAT and not the port itself. A write to this register modifies the output latches that modifies the pins configured as outputs.

#### REGISTER 3-10: OLAT: OUTPUT LATCH REGISTER 0 (ADDR 0x0A)

| R/W-0 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| OL7   | OL6   | OL5   | OL4   | OL3   | OL2   | OL1   | OL0   |
| bit 7 |       |       |       |       |       |       | bit 0 |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 7-0 **OL<7:0>:** Reflects the logic level on the output latch <7:0>

1 = Logic-high

0 = Logic-low

#### 3.6 Interrupt Logic

If enabled, MCP23X17 activates the INTn interrupt output when one of the port pins changes state or when a pin does not match the preconfigured default. Each pin is individually configurable as follows:

- Enable/disable interrupt via GPINTEN.
- Can interrupt on either pin change or change from default as configured in DEFVAL.

Both conditions are referred to as Interrupt-on-Change (IOC).

The interrupt control module uses the following registers/bits:

- IOCON.MIRROR controls if the two interrupt pins mirror each other.
- GPINTEN Interrupt enable register.
- · INTCON controls the source for the IOC.
- DEFVAL contains the register default for IOC operation.

#### 3.6.1 INTA AND INTB

There are two interrupt pins: INTA and INTB. By default, INTA is associated with GPAn pins (PORTA) and INTB is associated with GPBn pins (PORTB). Each port has an independent signal which is cleared if its associated GPIO or INTCAP register is read.

#### 3.6.1.1 Mirroring the INT pins

Additionally, the INTn pins can be configured to mirror each other so that any interrupt will cause both pins to go active. This is controlled via IOCON.MIRROR.

If IOCON.MIRROR = 0, the internal signals are routed independently to the INTA and INTB pads.

If IOCON.MIRROR = 1, the internal signals are OR'ed together and routed to the INTn pads. In this case, the interrupt will only be cleared if the associated GPIO or INTCAP is read (see Table 3-6).

TABLE 3-6: INTERRUPT OPERATION (IOCON.MIRROR = 1)

(100014.14111(1(0)( - 1)						
Interrupt Condition	Read PORTn <sup>(1)</sup>	Interrupt Result				
GPIOA	PORTA	Clear				
GPIOA	PORTB	Unchanged				
CDIOD	PORTA	Unchanged				
GPIOB	PORTB	Clear				
	PORTA	Unchanged				
GPIOA and	PORTB	Unchanged				
GPIOB	Both PORTA and PORTB	Clear				

Note 1: PORTn = GPIOn or INTCAPn

#### 3.6.2 IOC FROM PIN CHANGE

If enabled, MCP23X17 generates an interrupt if a mismatch condition exists between the current port value and the previous port value. Only IOC-enabled pins will be compared. Refer to Registers 3-2 and 3-4.

#### 3.6.3 IOC FROM REGISTER DEFAULT

If enabled, MCP23X17 generates an interrupt if a mismatch occurs between the DEFVAL register and the port. Only IOC enabled pins are compared. Refer to Registers 3-2, 3-3 and 3-4.

#### 3.6.4 INTERRUPT OPERATION

The INTn interrupt output can be configured as active-low, active-high or open-drain via the IOCON register.

Only those pins that are configured as an input (IODIR register) with Interrupt-On-Change (IOC) enabled (IOINTEN register) can cause an interrupt. Pins defined as an output have no effect on the interrupt output pin.

Input change activity on a port input pin that is enabled for IOC generates an internal device interrupt and the device captures the value of the port and copies it into INTCAP. The interrupt remains active until the INTCAP or GPIO register is read. Writing to these registers does not affect the interrupt. The interrupt condition is cleared after the LSb of the data is clocked out during a read command of GPIO or INTCAP.

The first interrupt event causes the port contents to be copied into the INTCAP register. Subsequent interrupt conditions on the port will not cause an interrupt to occur as long as the interrupt is not cleared by a read of INTCAP or GPIO.

Note: The value in INTCAP can be lost if GPIO is read before INTCAP while another IOC is pending. After reading GPIO, the interrupt will clear and then set due to the pending IOC, causing the INTCAP register to update.

#### 3.6.5 INTERRUPT CONDITIONS

There are two possible configurations that cause interrupts (configured via INTCON):

- Pins configured for interrupt-on-pin change will cause an interrupt to occur if a pin changes to the opposite state. The default state is reset after an interrupt occurs and after clearing the interrupt condition (i.e., after reading GPIO or INTCAP). For example, an interrupt occurs by an input changing from '1' to '0'. The new initial state for the pin is a logic '0' after the interrupt is cleared.
- Pins configured for interrupt-on-change from register value will cause an interrupt to occur if the corresponding input pin differs from the register bit. The interrupt condition will remain as long as the condition exists, regardless if the INTCAP or GPIO is read.

See Figures 3-8 and 3-9 for more information on interrupt operations.

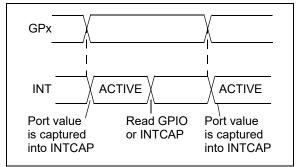
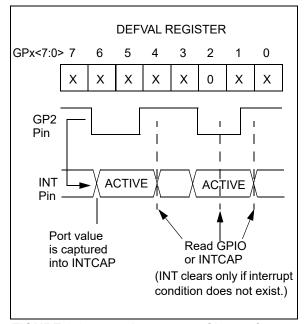


FIGURE 3-8: Interrupt-on-Pin Change.

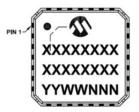


**FIGURE 3-9:** Interrupt-on-Change from Register Default.

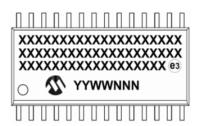
### 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

28-Lead QFN



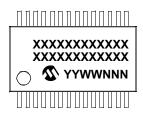
28-Lead SOIC



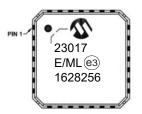
28-Lead SPDIP



28-Lead SSOP



Example:



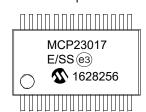
Example:



Example:



Example:



Legend: XX...X Product code or customer-specific information

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

Pb-free JEDEC® designator for Matte Tin (Sn)

\* This package is Pb-free. The Pb-free JEDEC designator ( ) can be found on the outer packaging for this package.

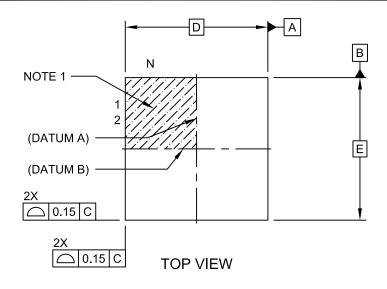
, ▲, ▼ Pin one index is identified by a dot, delta up, or delta down (triangle mark).

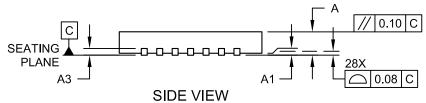
**Note**: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

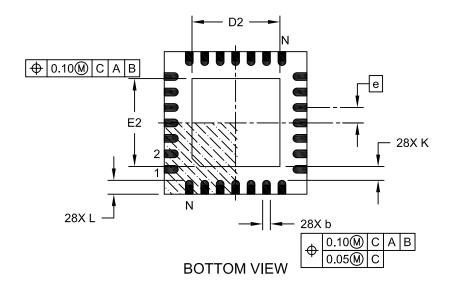
Underbar ( ) and/or Overbar ( ) symbol may not be to scale.

# 28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



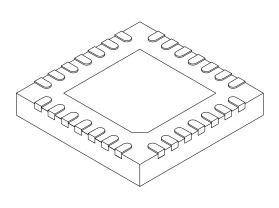




Microchip Technology Drawing C04-105C Sheet 1 of 2

# 28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	е		0.65 BSC	
Overall Height	Α	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Width	Е	6.00 BSC		
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Terminal Width	b	0.23	0.30	0.35
Terminal Length	Ĺ	0.50	0.55	0.70
Terminal-to-Exposed Pad	K	0.20	-	-

#### Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M.

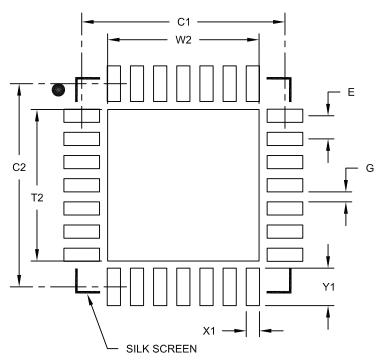
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105C Sheet 2 of 2

# 28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	MIN	NOM	MAX	
Contact Pitch	Е	0.65 BSC		
Optional Center Pad Width	W2			4.25
Optional Center Pad Length	T2			4.25
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.37
Contact Pad Length (X28)	Y1			1.00
Distance Between Pads	G	0.20		

#### Notes:

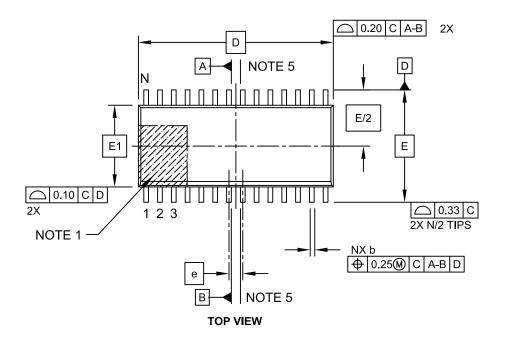
1. Dimensioning and tolerancing per ASME Y14.5M

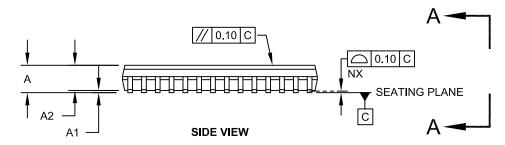
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

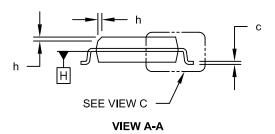
Microchip Technology Drawing No. C04-2105A

## 28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



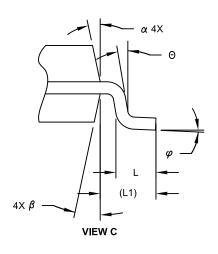


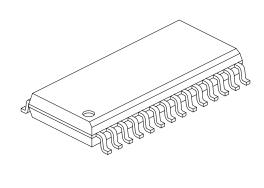


Microchip Technology Drawing C04-052C Sheet 1 of 2

## 28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





	MILLIMETERS			
Dimension	MIN	NOM	MAX	
Number of Pins	N		28	
Pitch	е		1.27 BSC	
Overall Height	Α	ı	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	Е	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	i
Foot Angle	φ	0°	-	8°
Lead Thickness	С	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

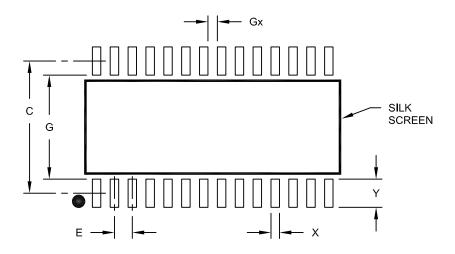
#### Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
  - REF: Reference Dimension, usually without tolerance, for information purposes only.
- 5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

### 28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



### RECOMMENDED LAND PATTERN

	Units			S
Dimension Limits		MIN	NOM	MAX
Contact Pitch	Е	1.27 BSC		
Contact Pad Spacing	С		9.40	
Contact Pad Width (X28)	Х			0.60
Contact Pad Length (X28)	Υ			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

#### Notes:

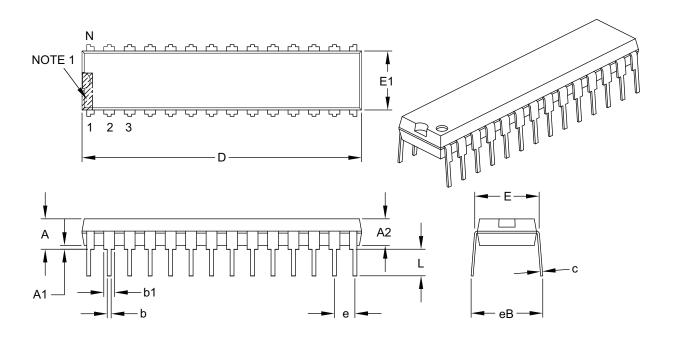
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

## 28-Lead Skinny Plastic Dual In-Line (SP) - 300 mil Body [SPDIP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		INCHES	
Dimension	n Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	е		.100 BSC	
Top to Seating Plane	Α	_	_	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	_	_
Shoulder to Shoulder Width	Е	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	С	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eВ	_	_	.430

#### Notes:

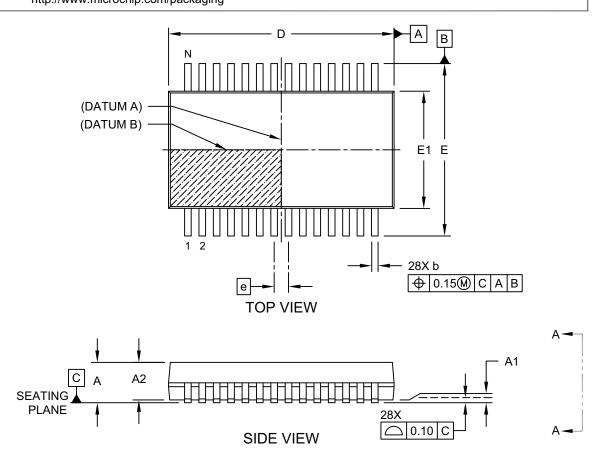
- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

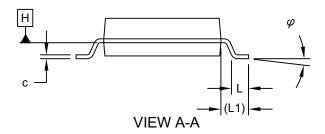
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

## 28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

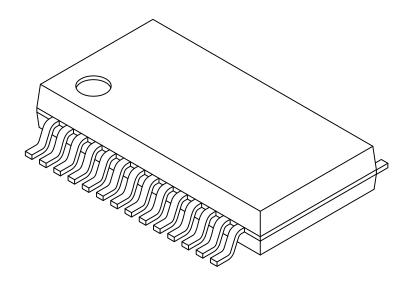




Microchip Technology Drawing C04-073 Rev C Sheet 1 of 2

## 28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension Limits		MIN	NOM	MAX
Number of Pins	Ν		28	
Pitch	е		0.65 BSC	
Overall Height	Α	-	1	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	-	1
Overall Width	Е	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	С	0.09	-	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	-	0.38

### Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20mm per side.
- 3. Dimensioning and tolerancing per ASME Y14.5M

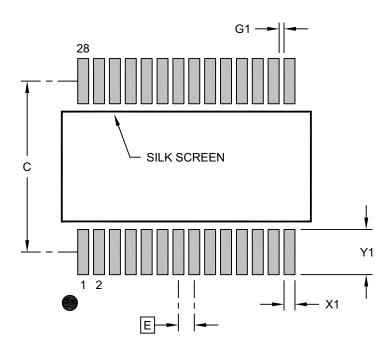
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073 Rev C Sheet 2 of 2

## 28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



### RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	MIN	NOM	MAX	
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	С		7.00	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.85
Contact Pad to Center Pad (X26)	G1	0.20		

#### Notes:

- Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- 2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2073 Rev B

### APPENDIX A: REVISION HISTORY

### **Revision D (June 2022)**

- · Updated description in Section "Features".
- Updated Table 2-1.
- Updated drawings for MCP23017 in Section "Package Types".
- Updated Section 3.5.1 "I/O Direction Register".
- Updated Section 4.1 "Package Marking Information".
- Updated Section "Product Identification System", with Automotive Qualified devices.
- Minor text and format changes throughout.

### Revision C (July 2016)

- Added ESD data to Section 1.0 "Electrical Characteristics".
- Updated Table 2-1.
- · Updated package outline drawings.
- · Minor typographical errors

### **Revision B (February 2007)**

- Changed Byte and Sequential Read in Figure 1-1 from "R" to "W".
- Table 2-4, Param No. 51 and 53: Changed from 450 to 600 and 500 to 600, respectively.
- · Added disclaimers to package outline drawings.
- · Updated package outline drawings.

### Revision A (June 2005)

· Original release of this document.

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	$[\dot{x}]_{(1)}$ $\dot{x}$ $\dot{x}$ $\dot{x}$			Examples:			
Device	Tape and Reel	Temperature	 Package	Qualification	a)	MCP23017-E/ML:	Extended Temperature, 28-Lead QFN package
	Option	Range			b)	MCP23017T-E/ML:	Tape and Reel, Extended temperature, 28-Lead QFN package
Device:	MCP23017: MCP23S17:		kpander with I <sup>2</sup> kpander with Sl		c)	MCP23017-E/SP:	Extended Temperature , 28-Lead SPDIP package
	_	(1)			d)	MCP23017-E/SO:	Extended Temperature, 28-Lead SOIC package
Tape and Reel Option:		Tape and Reel <sup>(1)</sup> Tube			e)	MCP23017T-E/SO:	Tape and Reel, Extended Temperature, 28-Lead SOIC package
Temperature	E =	–40°C to +125°C (	(Extended) *		f)	MCP23017-E/SS:	Extended Temperature, 28-Lead SSOP package
Range:	* While these devices are only offered in the "E" temperature range, the device will operate at different voltages and			g)	MCP23017T-E/SS:	Tape and Reel, Extended Temperature, 28-Lead SSOP package	
		temperatures as identified in Section 1.0 "Electrical Characteristics"			h)	MCP23017-E/SSVAO:	Extended Temperature, 28-Lead SSOP package, Automotive Qualified
Package:		Plastic Quad Flat, Body, QFN, 28-Le Plastic Small Outli	ad		i)	MCP23017T-E/SSVAO:	Tape and Reel, Extended Temperature, 28-Lead SSOP package, Automotive Qualified
	SP =	SOIC, 28-Lead Skinny Plastic Dual 28-Lead	al In-Line, 300 n	nil Body, SPDIP,	j)	MCP23S17-E/ML:	Extended Temperature, 28-Lead QFN package
	SS =	Plastic Shrink Sma SSOP, 28-Lead	all Outline, 5.30	) mm Body,	k)	MCP23S17T-E/ML:	Tape and Reel Extended Temperature, 28-Lead QFN package
Qualification:	<blank> = VAO =</blank>	Standard Part Automotive AEC-0	2100 Qualified		I)	MCP23S17-E/SP:	Extended Temperature, 28-Lead SPDIP package
	VAO -	Automotive ALC-C	2100 Qualified		m)	MCP23S17-E/SO:	Extended Temperature, 28-Lead SOIC package
					n)	MCP23S17T-E/SO:	Tape and Reel, Extended Temperature, 28-Lead SOIC package
					0)	MCP23S17-E/SS:	Extended Temperature, 28-Lead SSOP package
					p)	MCP23S17T-E/SS:	Tape and Reel, Extended Temperature, 28-Lead SSOP package
					q)	MCP23S17-E/SSVAO:	Extended Temperature, 28-Lead SSOP package, Automotive Qualified
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